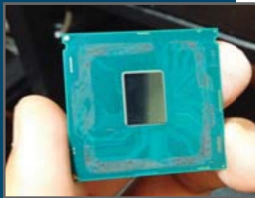
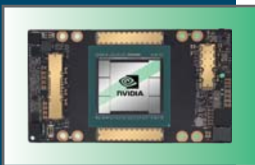
Advanced Packaging Update:
Market and Technology Trends

Vol. 1-0521





This issue of the Advanced Packaging Update features a detailed financial analysis of assembly service providers and an outlook for the remainder of 2021. Semiconductors, packaging material including substrates and leadframes, and assembly equipment are discussed. A special section on packaging trends for artificial intelligence (AI) from machine learning and training to edge computing is included. The market forecast for units of BGAs and CSPs is provided. The CSP market is divided into FBGA, FLGA, stacked die CSP, and QFN. Unit growth projections for Cu clip and package-on-package (PoP) are also provided.

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